

ABSTRACT OF THE DISCLOSURE:

TITLE: METHOD FOR TESTING MULTI-CHIP PACKAGES

5 A specialized computer program is utilized to
operate apparatus for testing internal components of an
integrated circuit package. A Peltier-junction module is
controlled so as to ramp-up and ramp-down the temperature
of an integrated circuit package while reading out and
plotting the power-bus-ground resistance of the package
during the up-ramp and down-ramp cycles. The computer
screen then indicates a characteristic graph for a
properly working package and erratic graph for a package
10 having a short circuit or open circuit components.

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